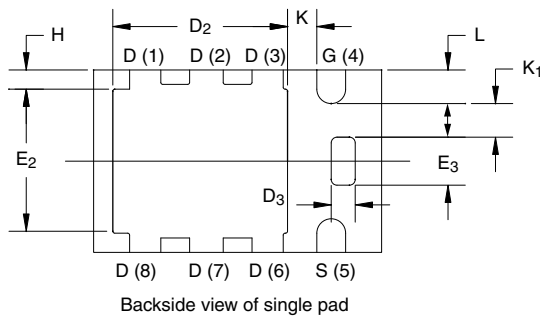
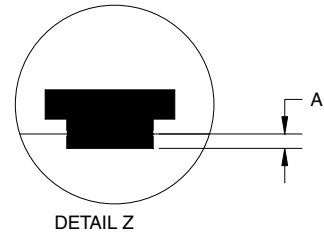
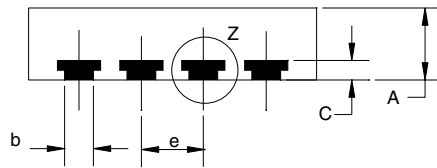
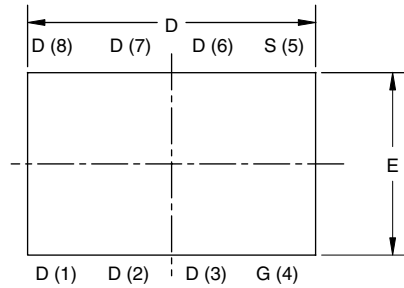
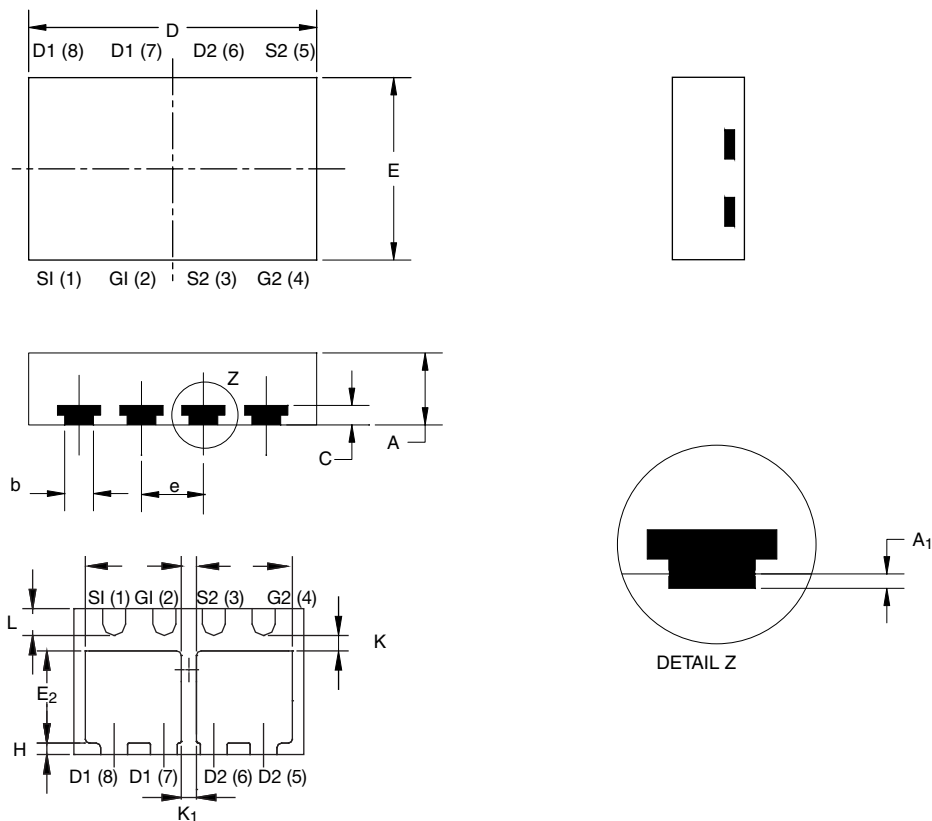


## PowerPAK® ChipFET® SINGLE PAD



DIM.	MILLIMETERS			INCHES		
	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.
A	0.70	0.75	0.85	0.028	0.030	0.033
A <sub>1</sub>	0	-	0.05	0	-	0.002
b	0.25	0.30	0.35	0.010	0.012	0.014
C	0.15	0.20	0.25	0.006	0.008	0.010
D	2.92	3.00	3.08	0.115	0.118	0.121
D <sub>2</sub>	1.75	1.87	2.00	0.069	0.074	0.079
D <sub>3</sub>	0.20	0.25	0.30	0.008	0.010	0.012
E	1.82	1.90	1.98	0.072	0.075	0.078
E <sub>2</sub>	1.38	1.50	1.63	0.054	0.059	0.064
E <sub>3</sub>	0.45	0.50	0.55	0.018	0.020	0.022
e	0.65 BSC			0.026 BSC		
H	0.15	0.20	0.25	0.006	0.008	0.010
K	0.25	-	-	0.010	-	-
K <sub>1</sub>	0.30	-	-	0.012	-	-
L	0.30	0.35	0.40	0.012	0.014	0.016

## PowerPAK® ChipFET® DUAL PAD



Backside view of dual pad

DIM.	MILLIMETERS			INCHES		
	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.
A	0.70	0.75	0.85	0.028	0.030	0.033
A <sub>1</sub>	0	-	0.05	0	-	0.002
b	0.25	0.30	0.35	0.010	0.012	0.014
C	0.15	0.20	0.25	0.006	0.008	0.010
D	2.92	3.00	3.08	0.115	0.118	0.121
D <sub>2</sub>	1.07	1.20	1.32	0.042	0.047	0.052
E	1.82	1.90	1.98	0.072	0.075	0.078
E <sub>2</sub>	0.92	1.05	1.17	0.036	0.041	0.046
e	0.65 BSC			0.026 BSC		
H	0.15	0.20	0.25	0.006	0.008	0.010
K	0.20	-	-	0.008	-	-
K <sub>1</sub>	0.20	-	-	0.008	-	-
L	0.30	0.35	0.40	0.012	0.014	0.016

ECN: C10-0618-Rev. C, 19-Jul-09

DWG: 5940